



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE9261BQX		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001687254						
<b>Package</b>		PG-VQFN-48-31		<b>Weight*</b>		129.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.471	1.91	1.91	19101	19101
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
		non noble metal	zinc	7440-66-6	0.072	0.06		554
		non noble metal	iron	7439-89-6	1.433	1.11		11077
wire	non noble metal	copper	7440-50-8	58.193	44.97	46.15	449766	461535
		copper	7440-50-8	0.545	0.42	0.42	4214	4214
		encapsulation	organic material	carbon black	1333-86-4	0.188	0.15	
	plastics	epoxy resin	-	7.958	6.15		61509	
		inorganic material	silicondioxide	60676-86-0	54.517	42.14	48.44	421358
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20067	20067
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4744	4744
glue	plastics	epoxy resin	-	0.179	0.14		1384	
		noble metal	silver	7440-22-4	0.600	0.46	0.60	4635
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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